

Sensors and Materials

**Special Issue on International Conference on BioSensors, BioElectronics,
BioMedical Devices, BioMEMS/NEMS and Applications 2019 (Bio4Apps 2019)**

Call for Papers

This special issue of *Sensors and Materials* aims to focus on bioelectronics, biosensors, biomedical devices, Bio-MEMS/NEMS and Sensing Biology with a strong emphasis on commercialization and applications. All articles related to these technology and applications are welcome.

Scope:

- Bio Sensors
 - Lab-on-chip
 - Miniaturized diagnostic
 - Novel bioelectric sensing
 - Nanophotonics/THz Sensing
 - Physiological monitoring
- Bio Electronics
 - Biomedical signal processing
 - Body area sensor networks
 - Circuits for biomedical applications/ devices
 - Flexible electronics
 - Implantable electronics
- BioMedical devices
 - Bio-imaging technology
 - Bio-compatible materials and packaging
 - Implantable medical devices
 - Prosthesis and Neural probes
 - Surgical robots
- BioMEMS/NEMS
 - Drug delivery
 - Energy harvesting technology
 - MEMS/NEMS for biomedical applications
 - Microfluidics for biomedical applications

Submission due date: March 31, 2020

Publication date (planned): Second half of 2020 – First half of 2021

Journal website: <https://myukk.org/>

Guest Editors: Prof. Masaya Miyazaki (Kyushu University)

and Assistant. Prof. Hirofumi Nogami (Kyushu University)

Submit to: Online Manuscript Submission System (<https://myukk-org.ssl-xserver.jp/form/>)

(Attention)

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication (for example, JPY 99360 for 10 pages in *Sensors and Materials* format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors will bear the proofreading fee (JPY 10000–15000), which will be charged with the publication fee.

If you have any questions, please feel free to contact the editorial staff at the address below.

Editorial Department of *Sensors and Materials*

MYU K.K.

1-23-3-303 Sendagi, Bunkyo-ku, Tokyo 113-0022, Japan

Tel: +81-3-3827-8549, Fax: +81-3-3827-8547

E-mail: myukk@myu-inc.jp

